



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/807,417	Confirmation No.: 3854
Applicant: R. Fazzio , Loveland, CO (US)	Art Unit: 2822
Filed: 03/23/2004	Examiner: LEWIS, Monica
Docket no.: 10030899-1	
Title: Microcap Wafer Bonding Method and Apparatus	

RESPONSE TO OFFICE ACTION UNDER 37 CFR 1.111  
AMENDMENTS UNDER 37 CFR 1.121

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir/Madam:

In response to the Office Action mailed March 1, 2006, the applicant submits the following:

**Title** is on page 2 of this paper.

**Claims** are listed beginning on page 3 of this paper.

**Remarks** begin on page 7 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: 06/01/2006

D. James Chung

**IN THE TITLE**

Please amend the Title as follows:

“Microcap Wafer Bonding ~~Method and~~ Apparatus”

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